

# MURD330T4G, SURD8330T4G

## SWITCHMODE Power Rectifier

### DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

#### Features

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- AEC-Q101 Qualified and PPAP Capable
- SURD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Package\*

#### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Rated Reverse Voltage	$V_R$	300	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 170^\circ\text{C}$ )	$I_F$	3.0	A
Non-Replicative Peak Surge Current	$I_{FSM}$	75	A
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

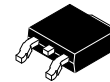
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



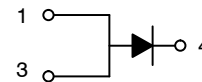
ON Semiconductor®

<http://onsemi.com>

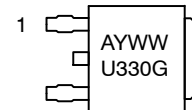
### ULTRAFAST RECTIFIER 3 A, 300 V



DPAK  
CASE 369C



#### MARKING DIAGRAM



U330 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping†
MURD330T4G	DPAK (Pb-Free)	2,500/Tape & Reel
SURD8330T4G	DPAK (Pb-Free)	2,500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MURD330T4G, SURD8330T4G

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{\theta JC}$	2	$^{\circ}\text{C}/\text{W}$
Thermal Resistance – Junction-to-Ambient (Note 1)	$R_{\theta JA}$	49	$^{\circ}\text{C}/\text{W}$

1. Rating applies when surface mounted on a 700 mm<sup>2</sup>, 1 oz Cu heat spreader.

## ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop ( $I_F = 3 \text{ A}$ , $T_J = 25^{\circ}\text{C}$ ) ( $I_F = 3 \text{ A}$ , $T_J = 150^{\circ}\text{C}$ )	$V_F$	1.15 0.92	V
Maximum Instantaneous Reverse Current ( $T_J = 25^{\circ}\text{C}$ , 300 V) ( $T_J = 150^{\circ}\text{C}$ , 300 V)	$I_R$	5 500	$\mu\text{A}$
Maximum Reverse Recovery Time ( $I_F = 1 \text{ A}$ , $di/dt = 50 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$ , $T_J = 25^{\circ}\text{C}$ )	$t_{rr}$	50	ns
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
Typical Peak Reverse Recovery Current ( $I_F = 1.0 \text{ A}$ , $di/dt = 50 \text{ A}/\mu\text{s}$ )	$I_{RM}$	1.5	A

## TYPICAL CHARACTERISTICS

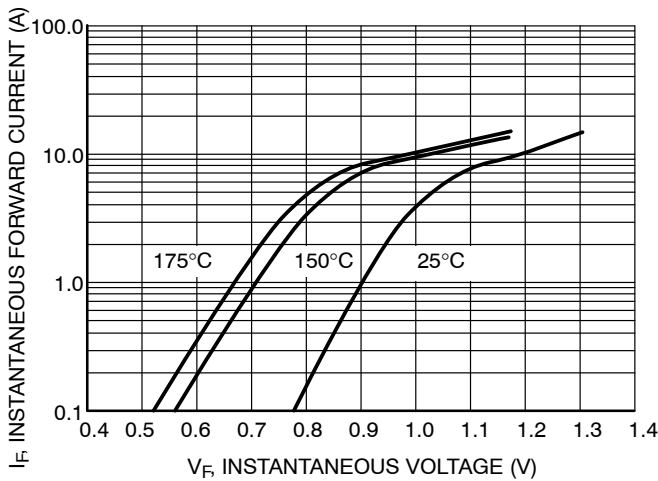


Figure 1. Typical Forward Voltage

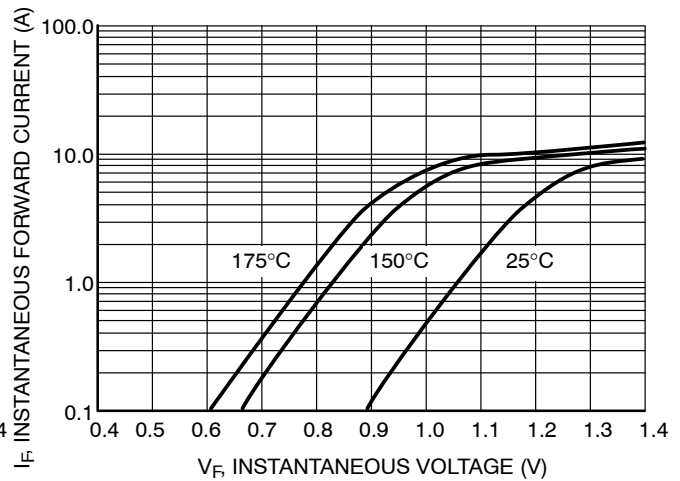


Figure 2. Maximum Forward Voltage

# MURD330T4G, SURD8330T4G

## TYPICAL CHARACTERISTICS

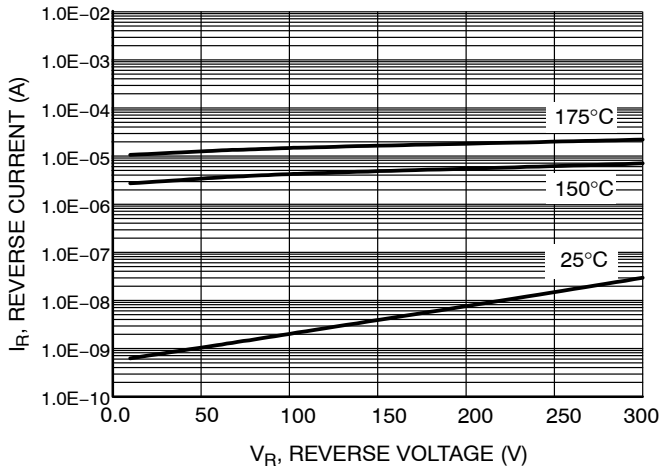


Figure 3. Typical Reverse Voltage

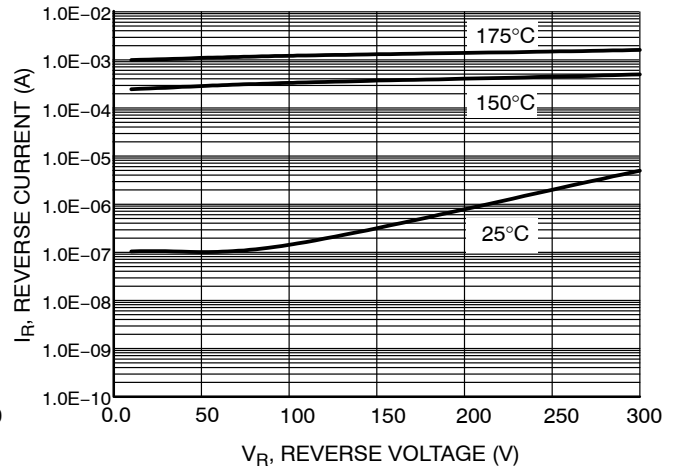


Figure 4. Maximum Reverse Voltage

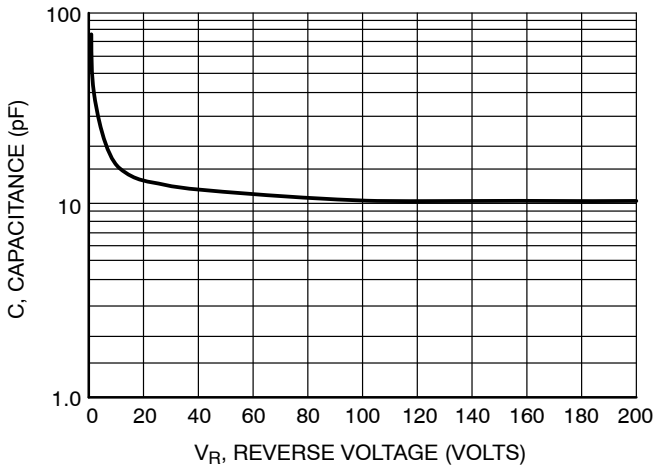


Figure 5. Typical Capacitance

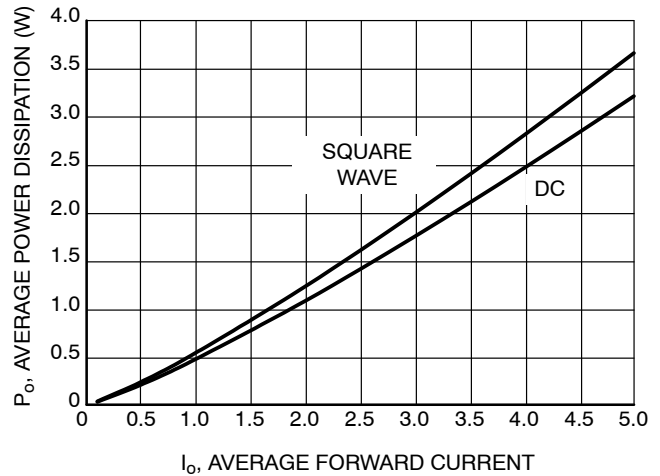


Figure 6. Power Dissipation

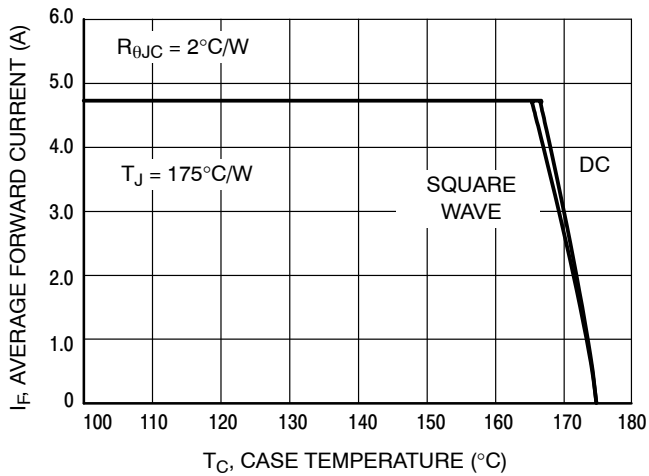


Figure 7. Current Derating, Case

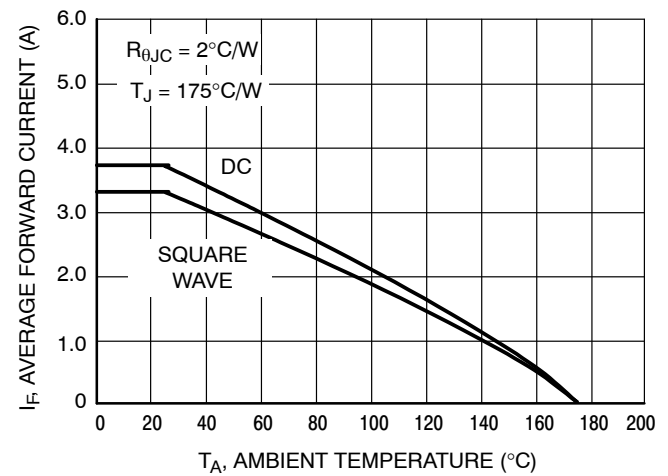
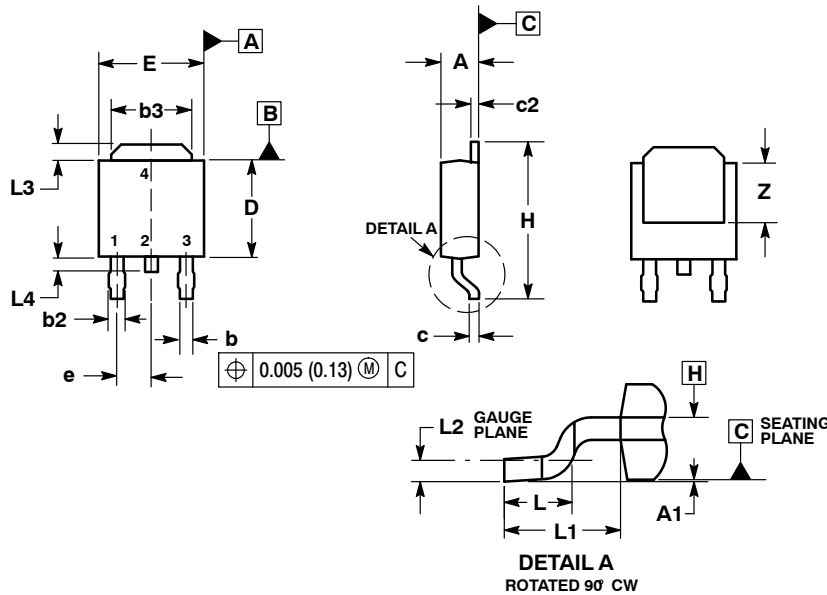


Figure 8. Current Derating, Ambient

# MURD330T4G, SURD8330T4G

## PACKAGE DIMENSIONS

### DPAK (SINGLE GAUGE) CASE 369C-01 ISSUE D

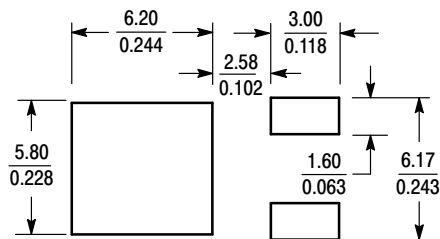


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.


DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

#### SOLDERING FOOTPRINT\*



SCALE 3:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### PUBLICATION ORDERING INFORMATION

##### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
Email: [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)

**Order Literature:** <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative